Emin ÃadÄ±rlÄ±

List of Publications by Year
in descending order

97 papers	2,315 citations	201674 27 h-index	254184 43 g-index
98 all docs	98 docs citations	98 times ranked	843 citing authors

#	Article	IF	Citations
1	Effect of Heat Treatment on the Microstructures and Mechanical Properties of Alâ€“4Cuâ€“1.5Mg Alloy. International Journal of Metalcasting, 2022, 16, 1020-1033.	1.9	5
2	Effect of Temperature Gradient and Growth Velocity on Microstructure and Mechanical Properties on Znâ€“7Alâ€“3Cu Ternary Eutectic Alloy. International Journal of Metalcasting, 2021, 15, 664-675.	1.9	1
3	Physical Properties of Directionally Solidified Al-1.9Mn-5Fe Alloy. Journal of Materials Engineering and Performance, 2021, 30, 1603-1610.	2.5	1
4	Investigation of the microstructure and physical properties of directionally solidified ternary Alâ€“8.8Laâ€“1.2Ni alloy. Journal of Alloys and Compounds, 2021, 855, 157331.	5.5	3
5	Investigation of the Thermal and Electrical Properties of Alâ€“1.9Mnâ€“xFe Ternary Alloys. Russian Journal of Non-Ferrous Metals, 2021, 62, 320-332.	0.6	0
6	EFFECT OF CU CONTENT AND GROWTH VELOCITY ON THE MICROSTRUCTURE PROPERTIES OF THE DIRECTIONALLY SOLIDIFIED AL-MN-CU TERNARY ALLOYS. EJONS International Journal of Mathematic Engineering and Natural Sciences, 2021, 5, 756-764.	0.0	0
7	Directionally Solidified Alâ€“Cuâ€“Siâ€“Fe Quaternary Eutectic Alloys. Physics of Metals and Metallography, 2020, 121, 78-83.	1.0	6
8	Effect of growth velocity on microstructure and mechanical properties of directionally solidified 7075 alloy. International Journal of Cast Metals Research, 2020, 33, 11-23.	1.0	7
9	Investigation of the thermo-electrical properties of A707 alloys. Thermochimica Acta, 2019, 673, 177-184.	2.7	3
10	Measurement and Prediction of the Thermal and Electrical Conductivity of Al-Zr Overhead Line Conductors at Elevated Temperatures. Materials Research, 2019, 22, .	1.3	12
11	Dependency of the thermal and electrical conductivity on temperatures and compositions of Zn in the Alâˆ'Zn alloys. International Journal of Cast Metals Research, 2019, 32, 95-105.	1.0	5
12	Investigation of the thermoelectrical properties of the Sn91.2â˜'xâ€“Zn8.8â€“Agx alloys. Journal of Thermal Analysis and Calorimetry, 2018, 132, 317-325.	3.6	10
13	Effect of Growth Velocity and Zn Content on Microhardness in Directionally Solidified Al-Zn Alloys. Materials Research, 2018, 21, .	1.3	1
14	Microstructural evolution and mechanical properties of Sn-Bi-Cu ternary eutectic alloy produced by directional solidification. Materials Research, 2018, 21, .	1.3	8
15	Microstructural, mechanical, electrical, and thermal properties of the Bi-Sn-Ag ternary eutectic alloy. Journal Wuhan University of Technology, Materials Science Edition, 2017, 32, 147-154.	1.0	3
16	Effects of Growth Rates and Compositions on Dendrite Arm Spacings in Directionally Solidified Al-Zn Alloys. Metallurgical and Materials Transactions A: Physical Metallurgy and Materials Science, 2017, 48, 5911-5923.	2.2	15
17	Effect of silicon content on microstructure, mechanical and electrical properties of the directionally solidified Alâ€“based quaternary alloys. Journal of Alloys and Compounds, 2017, 694, 471-479.	5.5	32
18	Influences of Growth Velocity and Fe Content on Microstructure, Microhardness and Tensile Properties of Directionally Solidified Al-1.9Mn-xFe Ternary Alloys. Materials Research, 2017, 20, 801-813.	1.3	8

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19	Microstructural Evolution and Mechanical Properties in Directionally Solidified Snâ€“10.2 Sb Peritectic Alloy at a Constant Temperature Gradient. Materials Research, 2016, 19, 370-378.	1.3	15
20	Effect of Growth Rate on the Microstructure and Microhardness in a Directionally Solidified Al-Zn-Mg Alloy. Metallurgical and Materials Transactions A: Physical Metallurgy and Materials Science, 2016, 47, 3040-3051.	2.2	19
21	Effect of heat treatment on the microstructures and mechanical properties of Al-5.5Zn-2.5Mg alloy. Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing, 2016, 662, 144-156.	5.6	37
22	Dependency of structure, mechanical and electrical properties on rotating magnetic field in the Biâ€“Snâ€“Ag ternary eutectic alloy. International Journal of Materials Research, 2016, 107, 362-371.	0.3	11
23	Effect of rotating magnetic field on the microstructures and physical properties of Alâ€“Cuâ€“Co ternary eutectic alloy. Journal of Alloys and Compounds, 2015, 647, 471-480.	5.5	29
24	Effect of heat treatments on the microhardness and tensile strength of Alâ€“0.25 wt.% Zr alloy. Journal of Alloys and Compounds, 2015, 632, 229-237.	5.5	40
25	Investigation of the Some Physical Properties of the Directionally Solidified Alâ€“Cuâ€“Co Ternary Eutectic Alloy. Transactions of the Indian Institute of Metals, 2015, 68, 817-827.	1.5	13
26	Characterization of a Directionally Solidified Snâ€“Pbâ€“Sb Ternary Eutectic Alloy. Metallography, Microstructure, and Analysis, 2015, 4, 286-297.	1.0	3
27	Mechanical, electrical, and thermal properties of the directionally solidified Bi-Zn-Al ternary eutectic alloy. International Journal of Minerals, Metallurgy and Materials, 2014, 21, 999-1008.	4.9	2
28	Thermo-electrical properties in Pb-Sb hypereutectic alloy. Metals and Materials International, 2013, 19, 465-472.	3.4	3
29	Influence of growth rate on microstructure, microhardness, and electrical resistivity of directionally solidified Al-7 wt% Ni hypo-eutectic alloy. Metals and Materials International, 2013, 19, 39-44.	3.4	44
30	Effect of solidification parameters on mechanical properties of directionally solidified Al-Rich Al-Cu alloys. Metals and Materials International, 2013, 19, 411-422.	3.4	60
31	Effect of solidification parameters on the microstructure of directionally solidified Sn-Bi-Zn lead-free solder. Metals and Materials International, 2012, 18, 349-354.	3.4	9
32	Variations of microhardness with solidification parameters and electrical resistivity with temperature for Alâ€“Cuâ€“Ag eutectic alloy. Current Applied Physics, 2012, 12, 7-10.	2.4	25
33	Measurements of the microhardness, electrical and thermal properties of the Alâ€“Ni eutectic alloy. Materials & Design, 2012, 34, 707-712.	5.1	64
34	Influence of temperature gradient and growth rate on the mechanical properties of directionally solidified Snâ€“3.5 wt% Ag eutectic solder. Journal of Materials Science: Materials in Electronics, 2012, 23, 31-40.	2.2	8
35	The effects of temperature gradient and growth rate on the microstructure of directionally solidified Snâ€“3.5Ag eutectic solder. Journal of Materials Science: Materials in Electronics, 2012, 23, 484-492.	2.2	15
36	Investigation of the microhardness and the electrical resistivity of undercooled Niâ€“10 at.% Si alloys. Journal of Non-Crystalline Solids, 2011, 357, 809-813.	3.1	10

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37	Determination of mechanical, electrical and thermal properties of the Snâ€•Biâ€•Zn ternary alloy. Journal of Non-Crystalline Solids, 2011, 357, 2876-2881.	3.1	33
38	Investigation of mechanical, electrical, and thermal properties of a Znâ€“1.26 wt% Al alloy. Journal of Materials Science, 2011, 46, 1414-1423.	3.7	4
39	The effect of composition on microhardness and determination of electrical and thermal properties in the Sn-Cu alloys. Journal of Materials Science: Materials in Electronics, 2011, 22, 1378-1386.	2.2	7
40	Dependence of electrical and thermal conductivity on temperature in directionally solidified Snâ€“3.5 wt% Ag eutectic alloy. Journal of Materials Science: Materials in Electronics, 2011, 22, 1709-1714.	2.2	9
41	Dependence of Electrical Resistivity on Temperature and Sn Content in Pb-Sn Solders. Journal of Electronic Materials, 2011, 40, 195-200.	2.2	22
42	Effects of Cooling Rate and Composition on Mechanical Properties of Directionally Solidified Pb100âˆ'x -Sn x Solders. Journal of Electronic Materials, 2011, 40, 1903-1911.	2.2	8
43	Investigation of the effect of composition on microhardness and determination of thermo-physical properties in the Znâ€“Cu alloys. Materials & Design, 2011, 32, 900-906.	5.1	13
44	SOLIDIFICATION CHARACTERISTICS AND MICROSTRUCTURAL EVOLUTION OF Zn-1.26wt.% Al ALLOY. Surface Review and Letters, 2011, 18, 281-288.	1.1	3
45	Determination of interfacial energies for solid al solution in equilibrium with Al-Cu-Ag liquid. Metals and Materials International, 2010, 16, 51-59.	3.4	10
46	Measurements of Microhardness and Thermal and Electrical Properties of the Binary Zn-0.7wt.%Cu Hypoperitectic Alloy. Journal of Electronic Materials, 2010, 39, 303-311.	2.2	17
47	Investigation of microhardness and thermo-electrical properties in the Snâ€“Cu hypereutectic alloy. Journal of Materials Science: Materials in Electronics, 2010, 21, 468-474.	2.2	13
48	Investigation of the effect of solidification processing parameters on the rod spacings and variation of microhardness with the rod spacing in the Snâ€“Cu hypereutectic alloy. Journal of Materials Science: Materials in Electronics, 2010, 21, 608-618.	2.2	15
49	Dependency of the thermal and electrical conductivity on the temperature and composition of Cu in the Al based Alâ€“Cu alloys. Experimental Thermal and Fluid Science, 2010, 34, 1507-1516.	2.7	62
50	Dependency of thermal and electrical conductivity on temperature and composition of Sn in Pbâ€“Sn alloys. Fluid Phase Equilibria, 2010, 295, 60-67.	2.5	21
51	Interfacial energies of solid CuAl2 in the CuAl2â€“Ag2Al pseudo binary alloy. Thin Solid Films, 2010, 518, 4322-4327.	1.8	9
52	Thermal conductivity and interfacial energies of solid Sn in the Snâ€“Cu alloy. Chemical Physics Letters, 2010, 484, 219-224.	2.6	14
53	INFLUENCE OF THE SOLIDIFICATION PARAMETERS ON DENDRITIC MICROSTRUCTURES IN UNSTEADY-STATE DIRECTIONALLY SOLIDIFIED OF LEADâ€“ANTIMONY ALLOY. Surface Review and Letters, 2010, 17, 477-486.	1.1	4
54	Characterization of rapidly solidified Niâ€“Si and Coâ€“Al eutectic alloys in drop tube. Journal of Non-Crystalline Solids, 2010, 356, 461-466.	3.1	27

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55	Microstructural, mechanical, electrical and thermal characterization of arc-melted Niâ€“Si and Coâ€“Si alloys. Journal of Non-Crystalline Solids, 2010, 356, 1735-1741.	3.1	11
56	Investigation of the effect of solidification processing parameters on microhardness and determination of thermoâ€“physical properties in the Znâ€“Cu peritectic alloy. Journal of Alloys and Compounds, 2010, 491, 143-148.	5.5	15
57	INFLUENCE OF GROWTH RATE ON MICROSTRUCTURE AND MICROINDENTATION HARDNESS OF DIRECTIONALLY SOLIDIFIED TINâ€“CADMIUM EUTECTIC ALLOY. Surface Review and Letters, 2009, 16, 191-201.	1.1	5
58	Determination of interfacial energies of solid Sn solution in the Inâ€“Biâ€“Sn ternary alloy. Materials Characterization, 2009, 60, 183-192.	4.4	12
59	The dependence of lamellar spacings and microhardness on the growth rate in the directionally solidified Bi-43 wt.% Sn alloy at a constant temperature gradient. Metals and Materials International, 2009, 15, 741-751.	3.4	12
60	Directional cellular growth of Al-2Âwt% Li bulk samples. Applied Physics A: Materials Science and Processing, 2009, 94, 155-165.	2.3	20
61	Directional solidification of Alâ€“Cuâ€“Ag alloy. Applied Physics A: Materials Science and Processing, 2009, 95, 923-932.	2.3	59
62	Unidirectional solidification of Zn-rich Zn-Cu hypoperitectic alloy. Journal of Materials Research, 2009, 24, 3422-3431.	2.6	14
63	Investigation of directional solidified Alâ€“Ti alloy. Journal of Non-Crystalline Solids, 2009, 355, 1231-1239.	3.1	5
64	The effect of growth rate on microstructure and microindentation hardness in the Inâ€“Biâ€“Sn ternary alloy at low melting point. Journal of Alloys and Compounds, 2009, 470, 150-156.	5.5	43
65	Dependency of microindentation hardness on solidification processing parameters and cellular spacing in the directionally solidified Al based alloys. Journal of Alloys and Compounds, 2009, 478, 281-286.	5.5	36
66	Experimental investigation of the effect of solidification processing parameters on the rod spacings in the Snâ€“1.2wt.% Cu alloy. Journal of Alloys and Compounds, 2009, 486, 199-206.	5.5	44
67	Experimental determination of solidâ€“solid and solidâ€“liquid interfacial energies of solid É› (CuZn5) in the Znâ€“Cu alloy. Journal of Alloys and Compounds, 2009, 487, 103-108.	5.5	10
68	Effects of growth rate and temperature gradient on the microstructure parameters in the directionally solidified succinonitrileâ€“7.5wt.% carbon tetrabromide alloy. Journal of Materials Processing Technology, 2008, 202, 145-155.	6.3	5
69	Variation of microindentation hardness with solidification and microstructure parameters in the Al based alloys. Applied Surface Science, 2008, 255, 3071-3078.	6.1	62
70	Interfacial Energy of Solid Bismuth in Equilibrium with Bi-In Eutectic Liquid at 109.5 â„ƒ Equilibrating Temperature. Metals and Materials International, 2008, 14, 177-187.	3.4	11
71	Dependency of Microstructural Parameters and Microindentation Hardness on the Temperature Gradient in the In-Bi-Sn Ternary Alloy with a Low Melting Point. Metals and Materials International, 2008, 14, 575-582.	3.4	18
72	Interfacial energy of solid In2Bi intermetallic phase in equilibrium with Inâ€“Bi eutectic liquid at 72ÂÂ°C equilibrating temperature. Materials Characterization, 2008, 59, 1101-1110.	4.4	20

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73	Natrolitite, an unusual rock â€“ occurrence and petrographic and geochemical characteristics (eastern) Tj ETQq1 1 0.784314 rgBT /Over	1.3	3
74	Determination of solidâ€“liquid interfacial energies in the Inâ€“Biâ€“Sn ternary alloy. Journal Physics D: Applied Physics, 2008, 41, 175302.	2.8	9
75	DENDRITIC GROWTH OF THE BINARY SUCCINONITRILE-CAMPHOR SYSTEM. Surface Review and Letters, 2007, 14, 1169-1179.	1.1	6
76	Measurement of solidâ€“liquid interfacial energy in the Inâ€“Bi eutectic alloy at low melting temperature. Journal of Physics Condensed Matter, 2007, 19, 506102.	1.8	16
77	Directional solidification and characterization of the Cdâ€“Sn eutectic alloy. Journal of Alloys and Compounds, 2007, 431, 171-179.	5.5	26
78	Effect of solidification processing parameters on the cellular spacings in the Alâ€“0.1wt% Ti and Alâ€“0.5wt% Ti alloys. Journal of Alloys and Compounds, 2007, 439, 114-127.	5.5	38
79	Eutectic growth of unidirectionally solidified bismuthâ€“cadmium alloy. Journal of Materials Processing Technology, 2007, 183, 310-320.	6.3	23
80	Dendritic Growth in an Aluminum-Silicon Alloy. Journal of Materials Engineering and Performance, 2007, 16, 12-21.	2.5	40
81	Temperature-Dependence of Electrical Resistivity of Cd-Sn, Bi-Sn, and Al-Si Eutectic and Al-3wt.%Si Hypoeutectic Alloys. Journal of Materials Engineering and Performance, 2006, 15, 490-493.	2.5	8
82	Dendritic solidification and characterization of a succinonitrileâ€“acetone alloy. Journal of Physics Condensed Matter, 2006, 18, 7825-7839.	1.8	12
83	Dependency of the dendritic arm spacings and tip radius on the growth rate and composition in the directionally solidified succinonitrileâ€“carbon tetrabromide alloys. Journal of Crystal Growth, 2005, 276, 583-593.	1.5	26
84	Effect of growth rate and lamellar spacing on microhardness in the directionally solidified Pb-Cd, Sn-Zn and Bi-Cd eutectic alloys. Journal of Materials Science, 2004, 39, 6571-6576.	3.7	39
85	Interflake spacings and undercoolings in Alâ€“Si irregular eutectic alloy. Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing, 2004, 369, 215-229.	5.6	83
86	Solidâ€“liquid interfacial energy in the Alâ€“Ti system. Materials Letters, 2004, 58, 3067-3073.	2.6	40
87	Effect of Growth Rates and Temperature Gradients on the Spacing and Undercooling in the Broken-Lamellar Eutectic Growth (Sn-Zn Eutectic System). Journal of Materials Engineering and Performance, 2003, 12, 456-469.	2.5	32
88	Effect of growth rates and temperature gradients on the lamellar spacing and the undercooling in the directionally solidified Pbâ€“Cd eutectic alloy. Materials Research Bulletin, 2003, 38, 1457-1476.	5.2	56
89	Effect of growth rate and composition on the primary spacing, the dendrite tip radius and mushy zone depth in the directionally solidified succinonitrileâ€“Salol alloys. Journal of Crystal Growth, 2003, 255, 190-203.	1.5	30
90	Directional solidification of aluminiumâ€“copper alloys. Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing, 2002, 327, 167-185.	5.6	303

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91	The dependence of lamellar spacing on growth rate and temperature gradient in the leadâ€"tin eutectic alloy. Journal of Materials Processing Technology, 2000, 97, 74-81.	6.3	59
92	Dependency of the microstructure parameters on the solidification parameters for camphene. Materials Research Bulletin, 2000, 35, 985-995.	5.2	34
93	The directional solidification of Pb-Sn alloys. Journal of Materials Science, 2000, 35, 3837-3848.	3.7	62
94	Solidâ€"liquid interfacial energy of camphene. Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing, 1999, 270, 343-348.	5.6	62
95	Title is missing!. Journal of Materials Science, 1999, 34, 5533-5541.	3.7	10
96	Solidâ€"liquid surface energy of pivalic acid. Journal of Crystal Growth, 1998, 194, 119-124.	1.5	77
97	The Effect of Growth Rate on the Microstructure and Mechanical Properties of 7020 Alloys. Journal of Materials Engineering and Performance, 0, , 1.	2.5	1